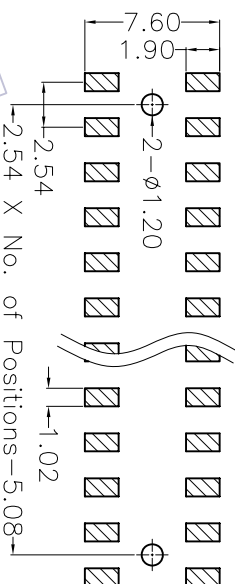
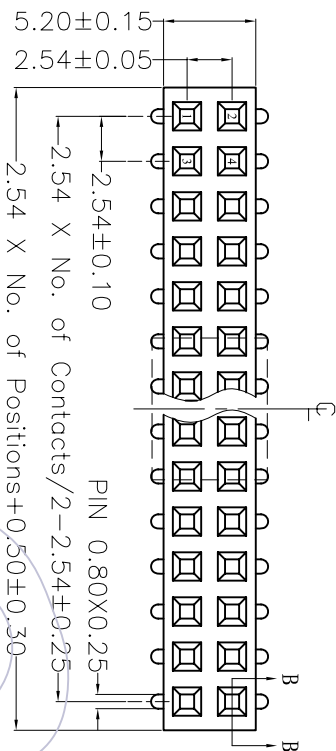


# HSP

**NOTES:**

Current Rating: 3.0AMP  
 Withstand Voltage: 500V AC/DC  
 Contact Resistance: 20mΩ Max  
 Insulation Resistance: 1000MΩMin  
 Operation Temperature: -40°C to +105°C

Contact Material: Phosphor Bronze  
 Contact plating: Au or Sn over Ni  
 Insulator Material: PA6T+30%G. F UL94V-0



Recommended P.C.B Layout(TOP Side)  
 (PCB BOARD TOLERANCE±0.05)

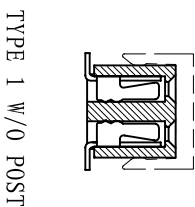
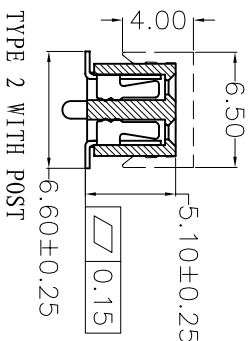
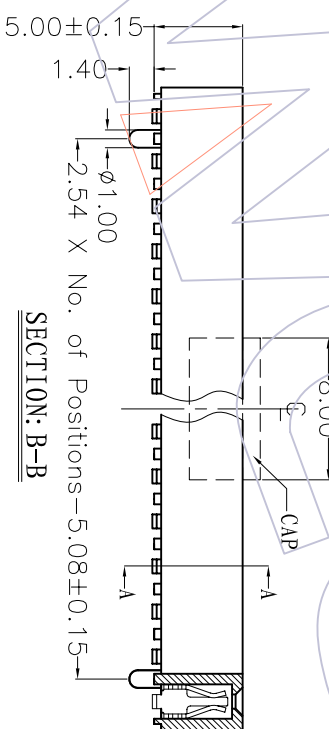
## Ordering Information

2150 - 2 XX M XX C U N T X

No. of Pins per ROW: 02-40/1N  
 Contact Plating: GO=Gold Flash  
 GI=3μ"Gold  
 GS=5μ"Gold  
 GA=10μ"Gold  
 GS=30μ"Gold  
 SO=Gold Flash/Tm  
 SI=3μ"Gold/Tm  
 S2=5μ"Gold/Tm  
 S3=10μ"Gold/Tm  
 S4=5μ"Gold/Tm  
 S5=30μ"Gold/Tm  
 SN=Tm

Packing: T=tube  
 P=tube+CAP  
 R=tube&rest+CAP

Series No. 1=TYPE 1  
 2=TYPE 2



| TYPE   | PART NO.         |
|--------|------------------|
| TYPE 1 | 2150-2XXMXXCUNX1 |
| TYPE 2 | 2150-2XXMXXCUNX2 |

**WCON** 维峰五金电子有限公司  
 WAVE HARDWARE ELECTRONICS CO. LTD

SEE TABLE

FH2.54 DUAL SMT H=3.5

| REV | DATE     | MODIFICATION DESCRIPTION | CHANGE | APPROVE | OPERATION         | DRAW             | WEIXD | 08.03.11 | SCALE | UNIT   | SIZE | PART NO. | TITLE: | PROJ. | Customer NO. |
|-----|----------|--------------------------|--------|---------|-------------------|------------------|-------|----------|-------|--------|------|----------|--------|-------|--------------|
| A0  | 08/03/01 | NEW                      |        |         | XXX<br>XXX<br>XXX | DESIGN<br>CHECK  |       |          | 3:1   | mm     | A4   |          |        |       |              |
| REV | DATE     | MODIFICATION DESCRIPTION | CHANGE | APPROVE | Angle<br>DIM      | CHECK<br>APPROVE |       |          | ± 3'  | ± 0.15 | 1/1  |          |        |       |              |